



## **Declaration, Power of Attorney and Petition**

Page 1 of 3

WE (I) the undersigned inventor(s), hereby declare(s) that:

My residence, post office address and citizenship are as stated below next to my name,

We (I) believe that we are (I am) the original, first and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## HEAT-CONDUCTING MULTILAYER SUBSTRATE AND POWER MODULE SUBSTRATE the specification of which is attached hereto. was filed on <u>December 23, 2003</u> as 10/743, 081 Application Serial No. and amended on was filed as PCT international application Number and was amended under PCT Article 19 \_\_\_\_\_ (if applicable). We (I) hereby state that we (I) have reviewed and understand the contents of the above-identified specification,

including the claims, as amended by any amendment referred to above.

We (I) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

We (I) hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed. Prior Foreign Application(s)

Application No.	Country	Day/Month/Year	Priority Claimed
2002-380401	Japan	27/12/2002	⊠ Yes □ No
2003-397839	Japan	27/11/2003	⊠ Yes □ No
			☐ Yes ☐ No
			☐ Yes ☐ No

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Page 2 of 3 Declaration

We (I) hereby claim the benefit under Trapplication(s) listed below.	itle 35, United Sta	ates Code, § 119(e) of any United States provisional	
(Application Number)		(Filing Date)	
(Application Number)		(Filing Date)	
any PCT International application designatin each of the claims of this application is not of the manner provided by the first paragraph of	g the United State disclosed in the pr 35 U.S.C. § 112, FR § 1.56 which	iny United States application(s), or under § 365(c) of es, listed below and, insofar as the subject matter of ior United States or PCT International application in acknowledge the duty to disclose information which became available between the filing date of the prior his application.	
Application Serial No.	Filing Date	Status (pending, patented, abandoned)	
And we (I) hereby appoint the following	g registered practit	oner(s):	
	22850		
		cation, to prosecute this application and to transact all nereby request that all correspondence regarding this	
	22850		
on information and belief are believed to be that willful false statements and the like so ma	erein of our (my) true; and further t ade are punishable	own knowledge are true and that all statements made hat these statements were made with the knowledge by fine or imprisonment, or both, under Section 1001 false statements may jeopardize the validity of the	
Yoshiyuki NAGATOMO NAME OF FIRST SOLE INVENTOR	I	Residence: Gotenba-shi, Japan	
Yoshiyuki Ragatonno	-	Sitizen of Japan	
Signature of Inventor	<del></del>	Citizen of: Japan  Aailing Address: c/o MITSUBISHI MATERIALS	
		CORPORATION, Central Research Institute,	
May 24, 2004	7	Jaka Research Center, 1002-14, Mukaiyama, Naka-cho, Naka-gun, Jaraki-Keri, Japan	
Date		MINITED IN COLUMN	

## Page 3 of 3 Declaration

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NAME OF FOURTH JOINT INVENTOR	Residence:
NAME OF FOORTH JOINT INVENTOR	
	GW 4
Signature of Inventor	Citizen of:
	Mailing Address:
	<del></del>
Date	· · · · · · · · · · · · · · · · · · ·
	D 11
NAME OF FIFTH JOINT INVENTOR	Residence:
	· · · · · · · · · · · · · · · · · · ·
Signature of Inventor	Citizen of:
Signature of Hivertor	Mailing Address:
Date	